

MEMSLand

Cost Effective MEMS to Develop a Sustainable High Tech Business

BOSCHMAN

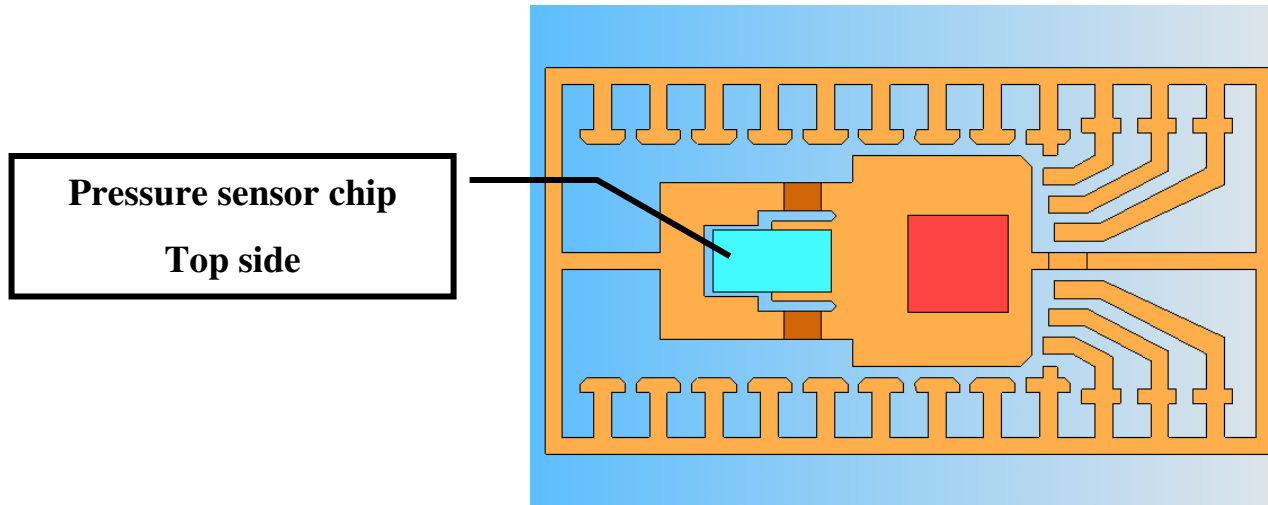
Pressure sensor molding

Consortium Meeting UT Twente June, 05, 2007

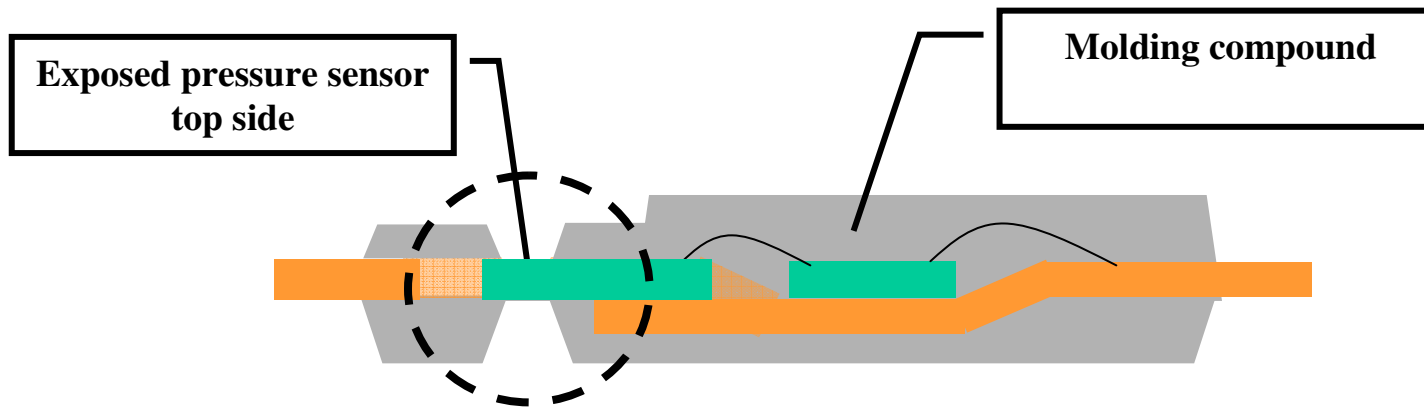
Project targets

- **Clean sensor surface windows. No sensor pollution by molding compound residue.**
- **No sensor membrane damage by molding process.**
- **Encapsulation technology capable to protect chips in very aggressive environments.**

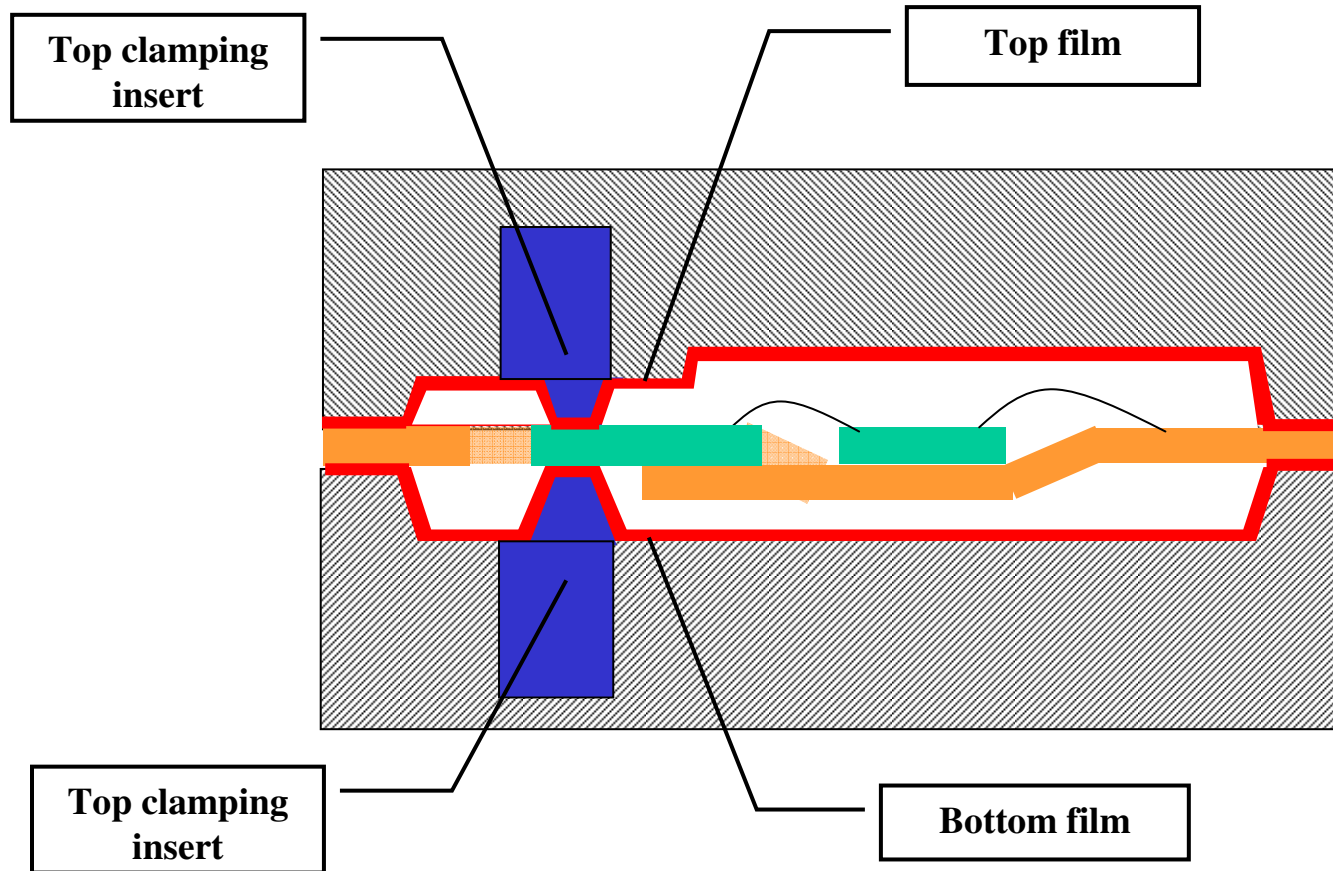
LEAD FRAME AND PRESSURE SENSOR CHIP



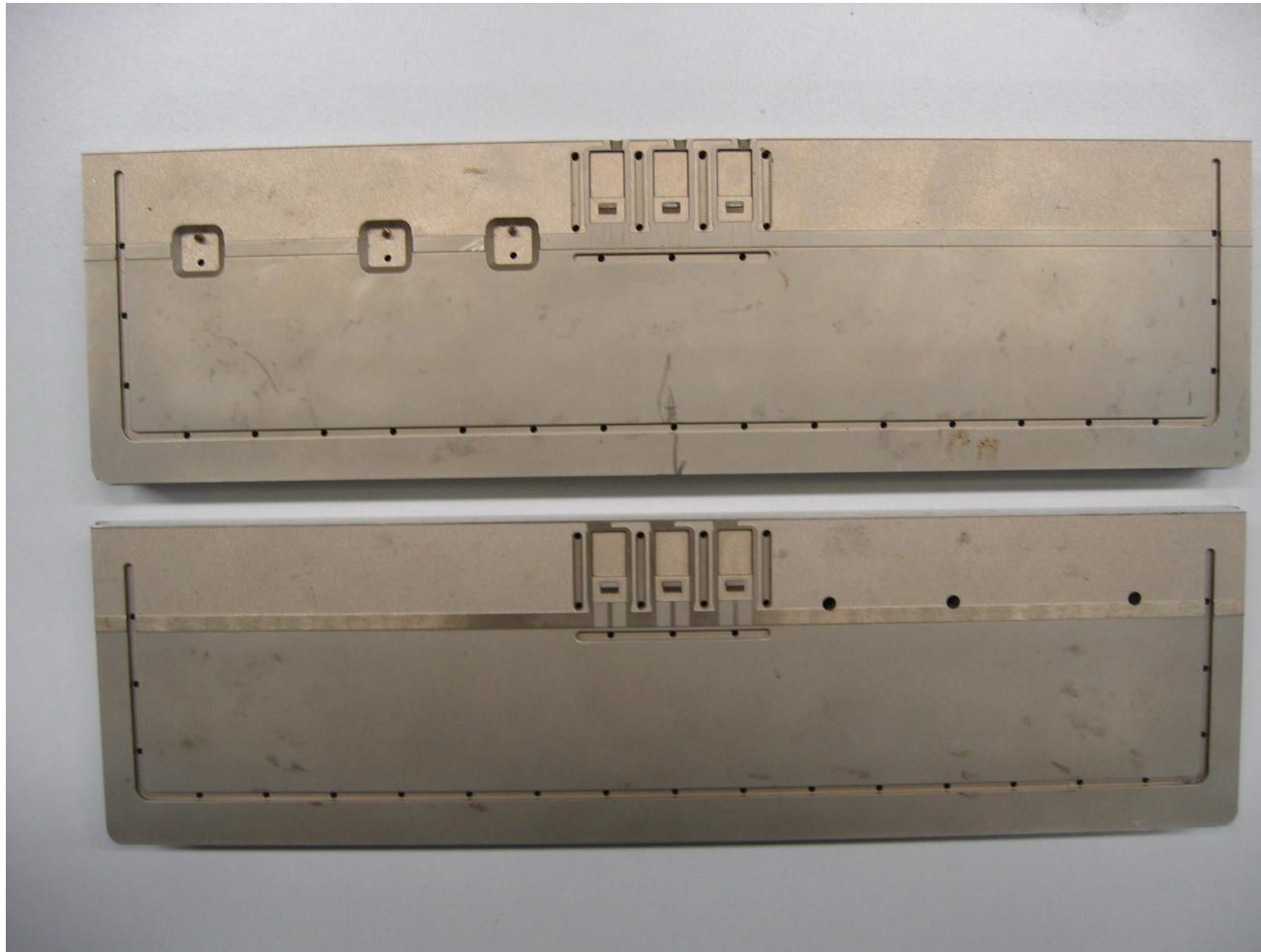
MOLDED PACKAGE WINDOWS FOR EXPOSED SENSOR



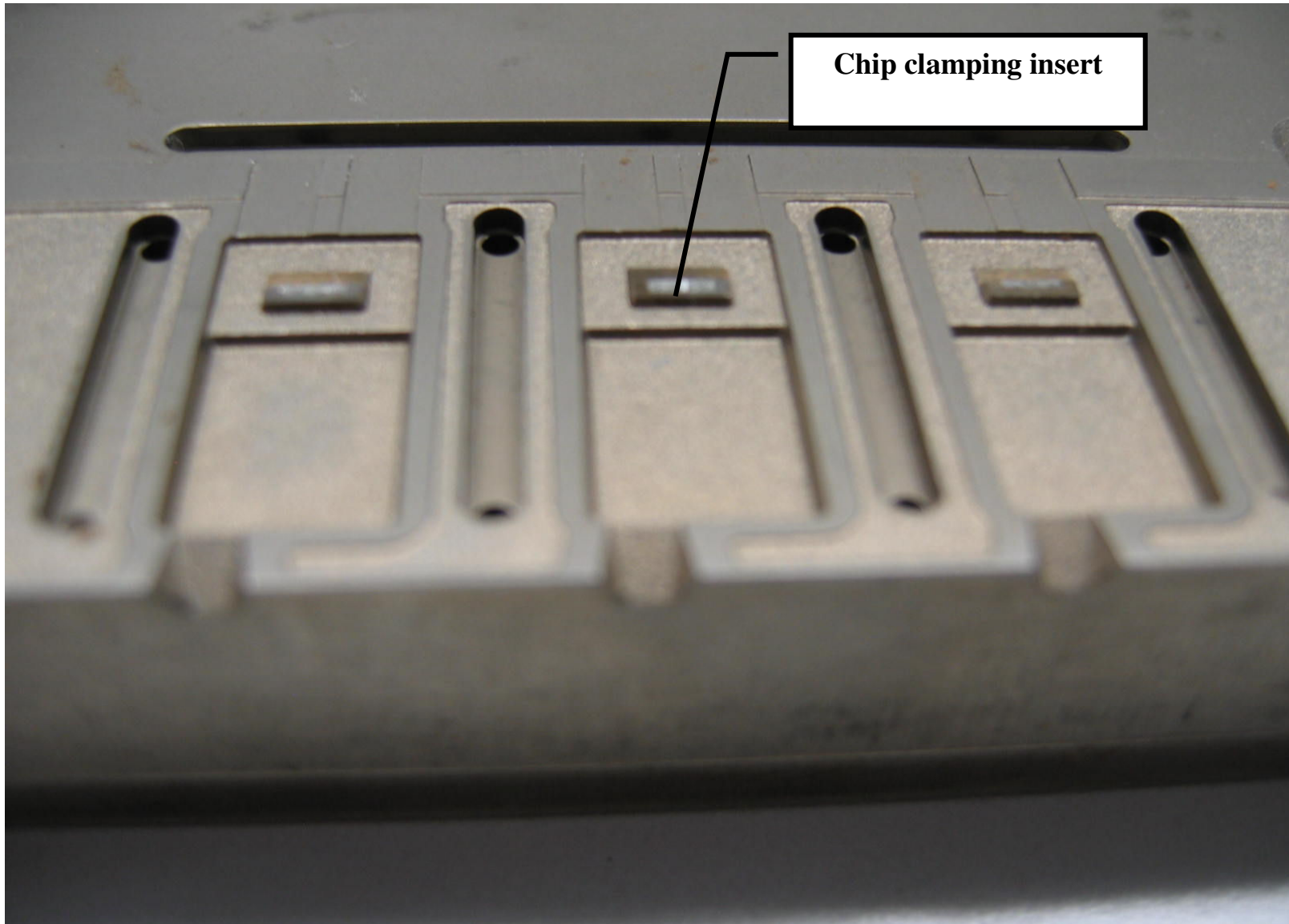
FILM TO KEEP SENSOR SURFACES CLEAN



TOP AND BOTTOM MOLD CAVITY STRIPS



CHIP MOLD CLAMPING INSERTS



Project status

- **Pressure sensor can be molded with Film Assisted Molding process.**
- **Clean sensor surfaces can be obtained.**
- **Film can protect the sensor membrane sufficiently without damage.**
- **Project is on time.**